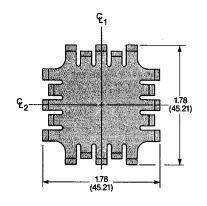


METAL CASE, CASE-MOUNTED SEMICONDUCTORS

UP1 Series for TO-3 Outline and Stud Mount Devices

Natural Conv. (°C/W): 10.4 Forced Air (°C/W): 3.2 Mounting Envelope: 1.78" x 1.78" x .50"







UP1-TO3-CB w/2N3055 (TO-3) TRANSISTOR CASE TEMP. RISE ABOVE AMBIENT (°C) 1 2 2 4 5 9 2 0 6 6 00 1 2 2 4 5 9 2 0 8 6 00 D B Ε 4 6 8 10 12 14 16 18 20 22 24 26 28 30 0 2 POWER DISSIPATED (WATTS)

DESCRIPTION OF CURVES

- Α. N.C. Horiz. Device Only
- Mounted to G-10. N.C Horiz. & Vert. With
- Β. Dissipator.
- C. 200 FPM w/Diss.
- 500 FPM w/Diss. D.
- 1000 FPM w/Diss. E.

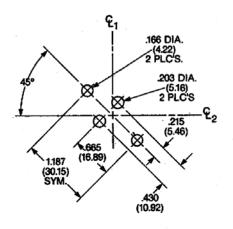
- Thermal Resistance Case to Sink is 0.1-0.3 °C/W w/Joint Compound.
- Derate 0.7 °C/watt for unplated part in natural convection only.
- Derate 0.4 °C/watt for Insulube® part in natural convection only.

Ordering Information

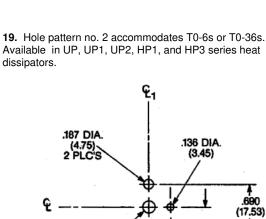
CTS IERC PART NO.			Semiconductor	Hole patt.	Max. Weight
Unplated	Comm'l. Black Anodize	Mil. Black Anodize	Accommodated	ref. no.	(Grams)
UP1-000-U	UP1-000-CB	UP1-000-B	Undrilled		15.5
UP1-T03-U	UP1-T03-CB	UP1-T03-B	T0-3	16	15.5
UP1-T03-46U	UP1-T03-46CB	UP1-T03-46B	T0-3 IC	17	15.5
UP1-436-U	UP1-436-CB	UP1-436-B	TO-3 (4-pin)	18	15.5
UP1-T06-U	UP1-T06-CB	UP1-T06-B	T0-6, T0-36	19	15.5
UP1-T015-U	UP1-T015-CB	UP1-T015-B	T0-15, D0-5	23	15.5
UP-420-U	UP1-420-CB	UP1-420-B	Universal	27	15.5
UP1-T0V-7U	UP1-T0V-7CB	UP1-T0V-7B	Universal	28	15.5

HOLE PATTERNS

16. Hole pattern no. 1 accommodates T0-3s. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



18. Hole pattern no. 436 accommodates t0-3s (4-pin). Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



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.206 DIA. (5.23)

.345 (8.76)

17. Hole pattern no. 202 accommodates T0-3 ICs. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.

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.098 DIA. 8 PLC'S (2.43) ON .500 DIA. B.C.

7 <u>PLC</u>'S

80

YP.

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.345 (8.76)

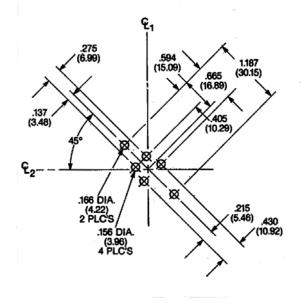
.152 DIA.

(3.86) 2 PLC'S

¥.593 (15.06)

1.187 (30.15)





23. Hole pattern no. 3 accommodates T0-15s, D0-5s and other $\frac{1}{4}$ stud mount devices. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.

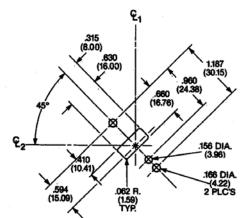
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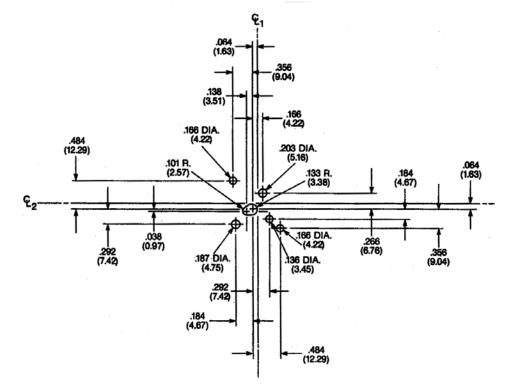
266 DIA.

(6.76)

d other 1, and **27.** Hole pattern no. 420 (Universal) accommodates T0-3s, T0-66s, T0-126s, T0-127s, or T0-220s. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



28. Hole pattern no. 64 (Universal) accommodates T0-3s, D0-4s, T0-15s, T0-6s, T0-36s, or other stud mounted devices up to ¼" diameter. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.





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